

L Number	Hits	Search Text	DB	Time stamp
2	2063	("etch stop" or "polish stop") and (opening or via ) and (liner or barrier) and (copper or Cu or tungsten or W)	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:39
5	278	("etch stop" or "polish stop") and (opening or via ) and (liner or barrier) and (copper or Cu or tungsten or W)) and "hard mask"	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:43
6	211	((("etch stop" or "polish stop") and (opening or via ) and (liner or barrier) and (copper or Cu or tungsten or W)) and "hard mask") and ("chemical mechanical polishing" or CMP )	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:44
7	37	((DLC or "diamond like carbon") same ("etch stop" or "polish stop"))	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:47
9	18599	"chemical mechanical polishing" or CMP	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:56
10	1084	((("etch stop" or "polish stop") and (opening or via ) and (liner or barrier) and (copper or Cu or tungsten or W) ) and ("chemical mechanical polishing" or CMP )	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:56
11	157	(SiC or "silicon carbide") same "etch stop"	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:56
12	85	((SiC or "silicon carbide") same "etch stop") and ("chemical mechanical polishing" or CMP)	USPAT; EPO; JPO; IBM_TDB	2002/12/02 16:58